



US00D761214S

(12) **United States Design Patent**
Lee et al.

(10) **Patent No.:** **US D761,214 S**
(45) **Date of Patent:** **** Jul. 12, 2016**

(54) **LIGHT EMITTING DIODE PACKAGE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/522,733**

(22) Filed: **Apr. 2, 2015**

(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**

USPC D13/180; D26/1
CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/04; H01L 33/08; H01L 33/10;
H01L 33/20; H01L 33/38; H01L 33/42;
H01L 33/48; H01L 33/62; H01L 33/483;
H01L 33/486; F21K 9/00; F21K 9/30; F21K
9/54

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a light emitting diode package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a light emitting diode package showing our new design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a left side view thereof;

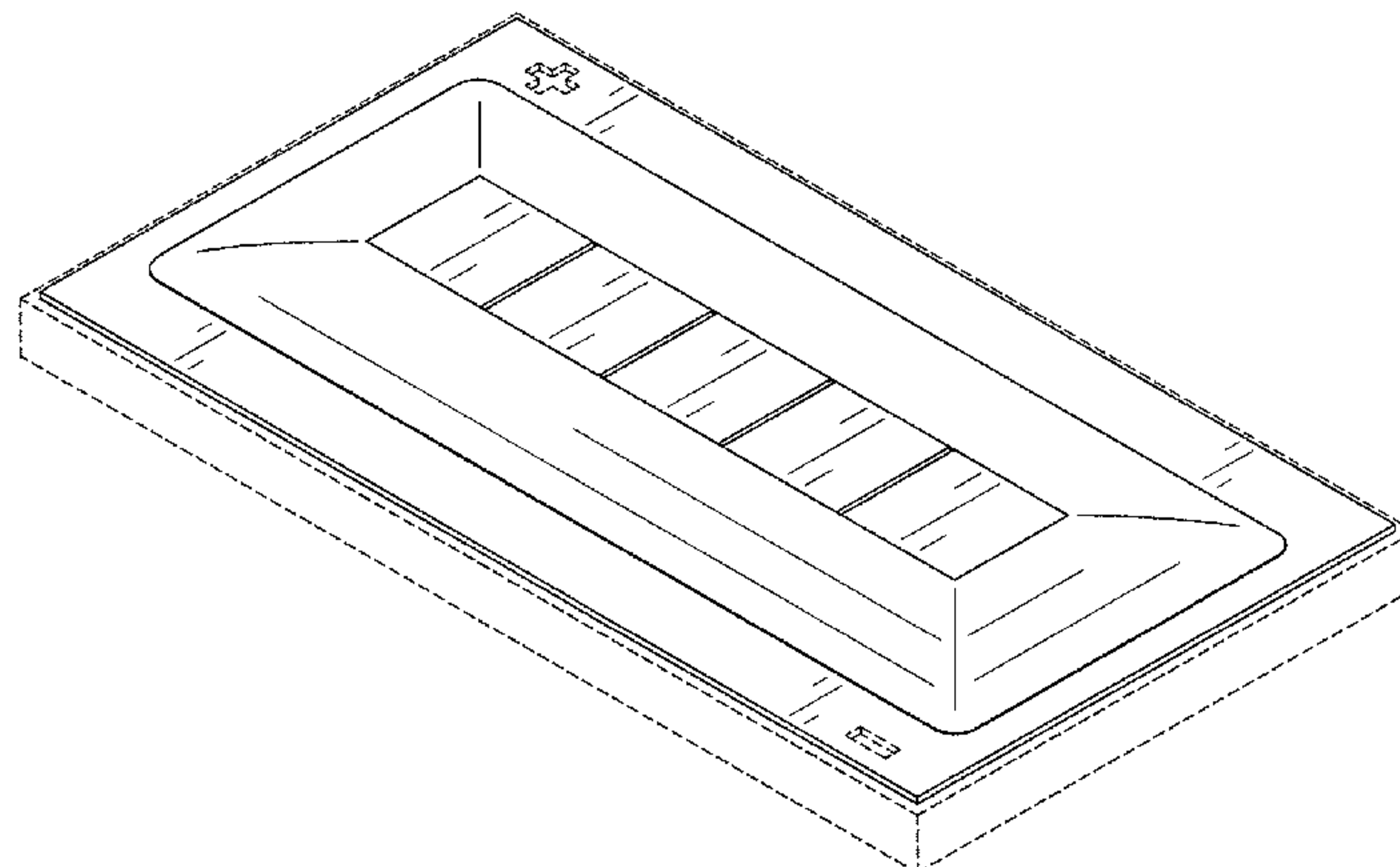
FIG. 5 is a right side view thereof;

FIG. 6 is top view thereof; and,

FIG. 7 is a bottom view thereof.

The broken lines are for the purpose of illustrating portions of the light emitting diode package form no part of the claimed design. The light shade lines on the surface portions indicate contour and not surface decoration.

1 Claim, 5 Drawing Sheets



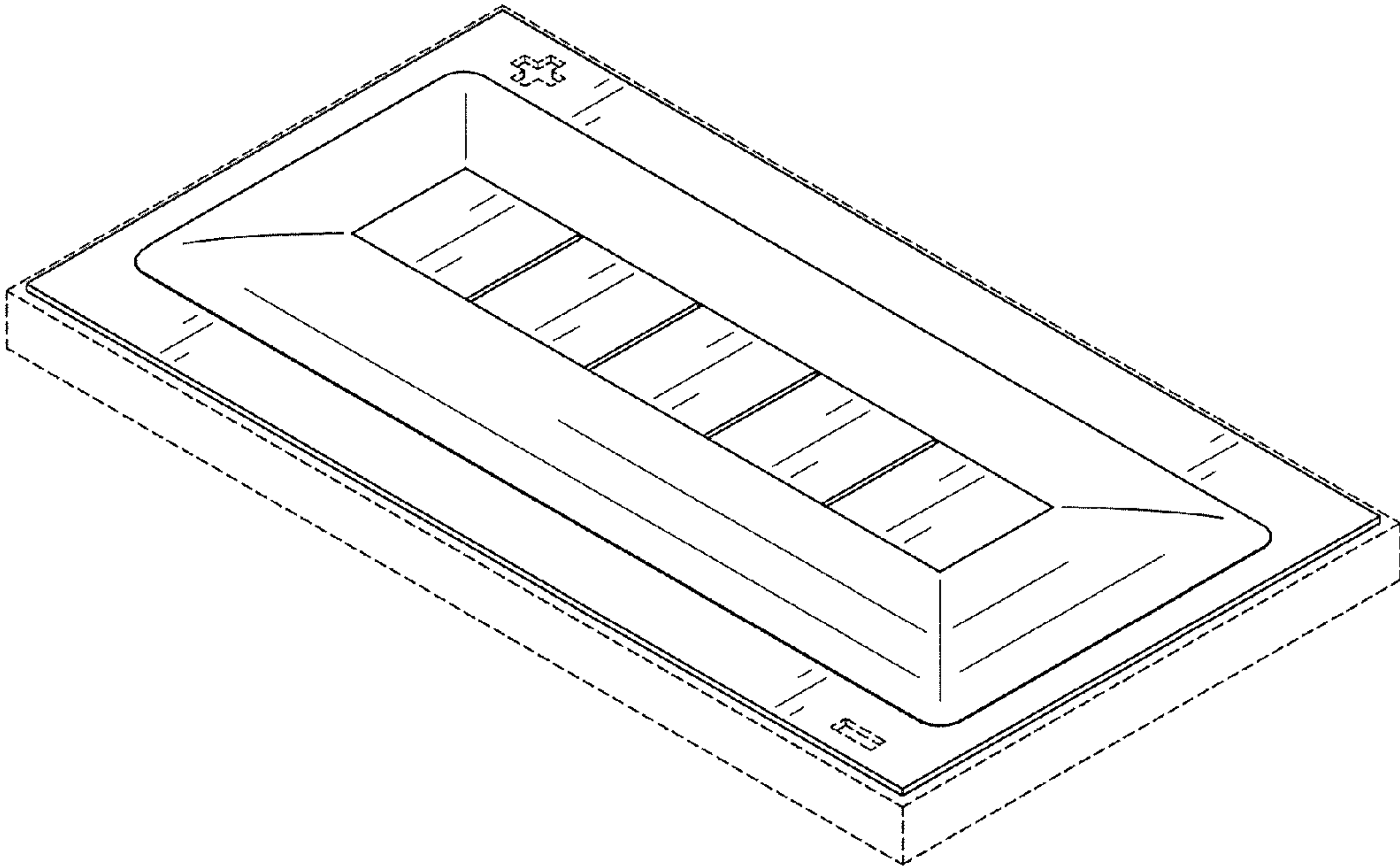


FIG. 1

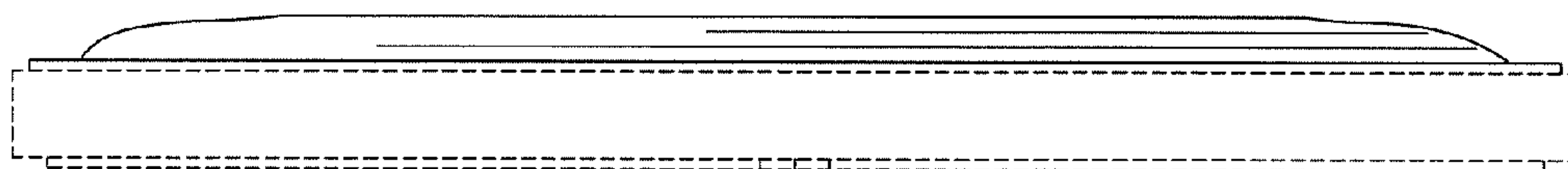


FIG. 2

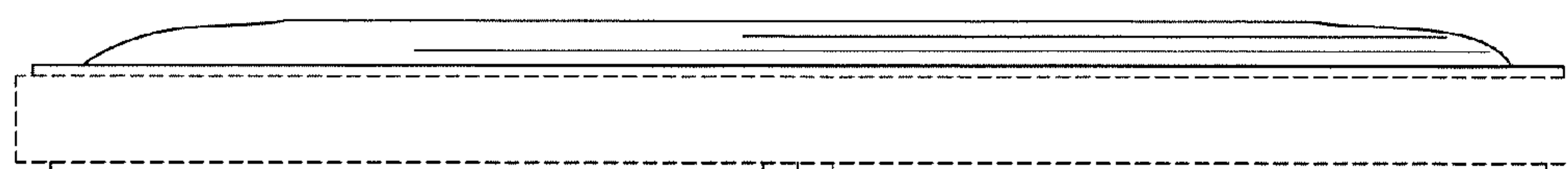


FIG. 3

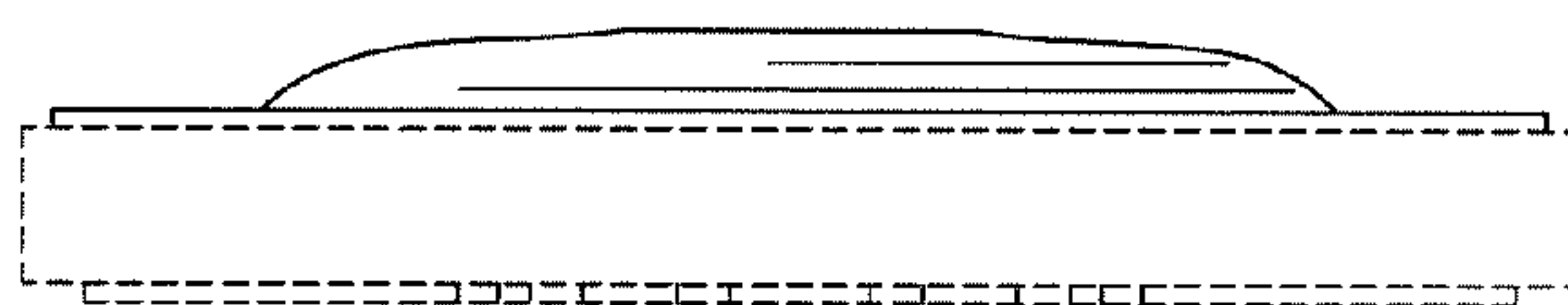


FIG. 4

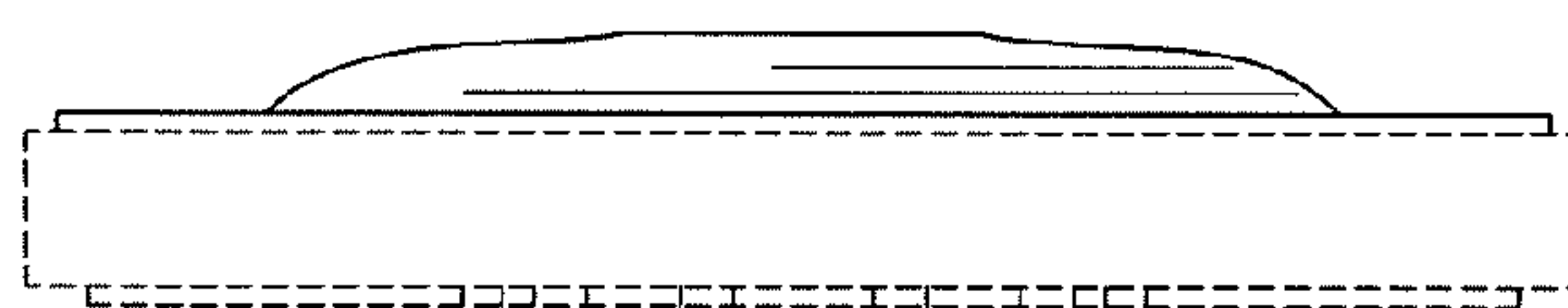


FIG. 5

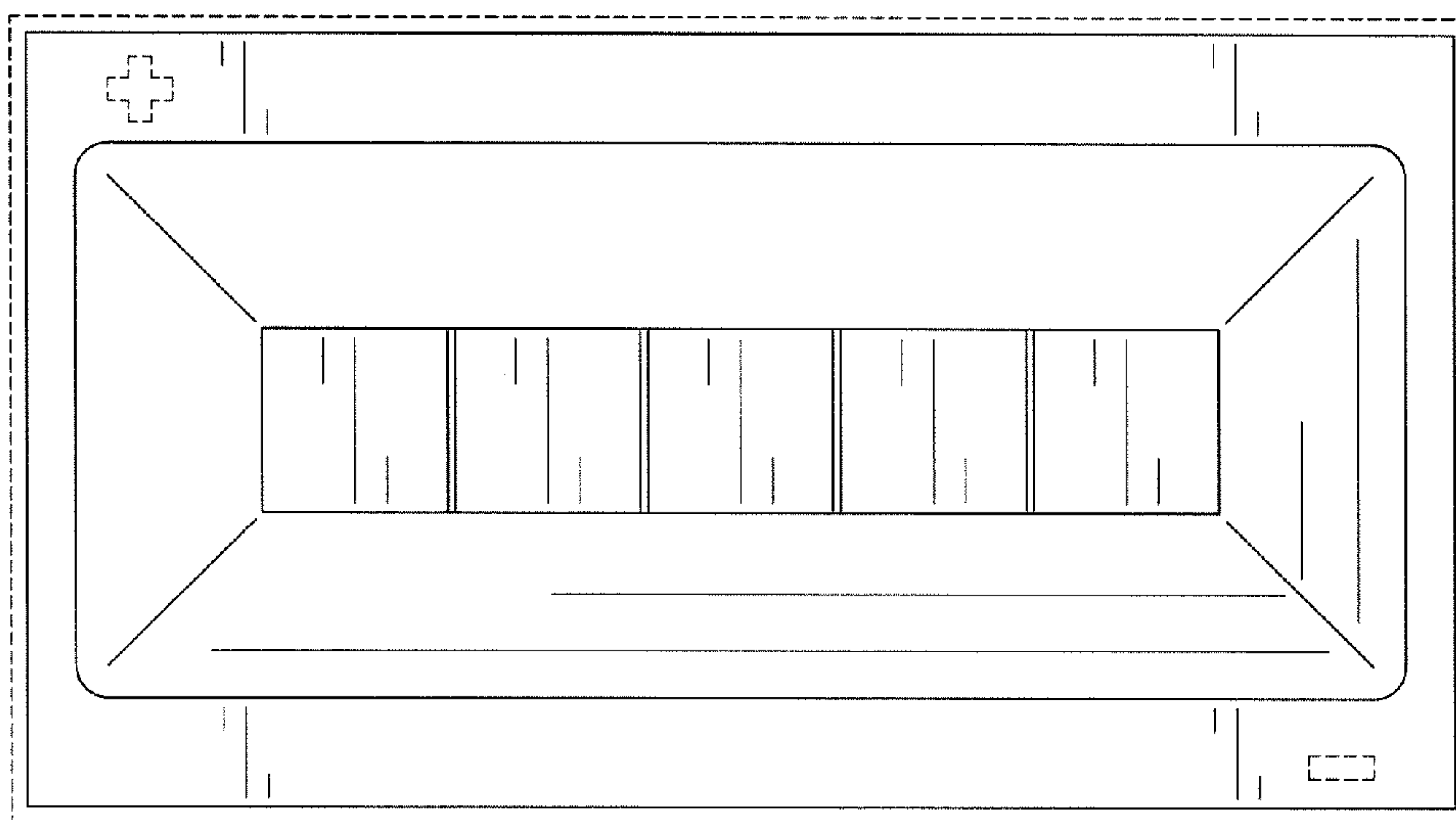


FIG. 6

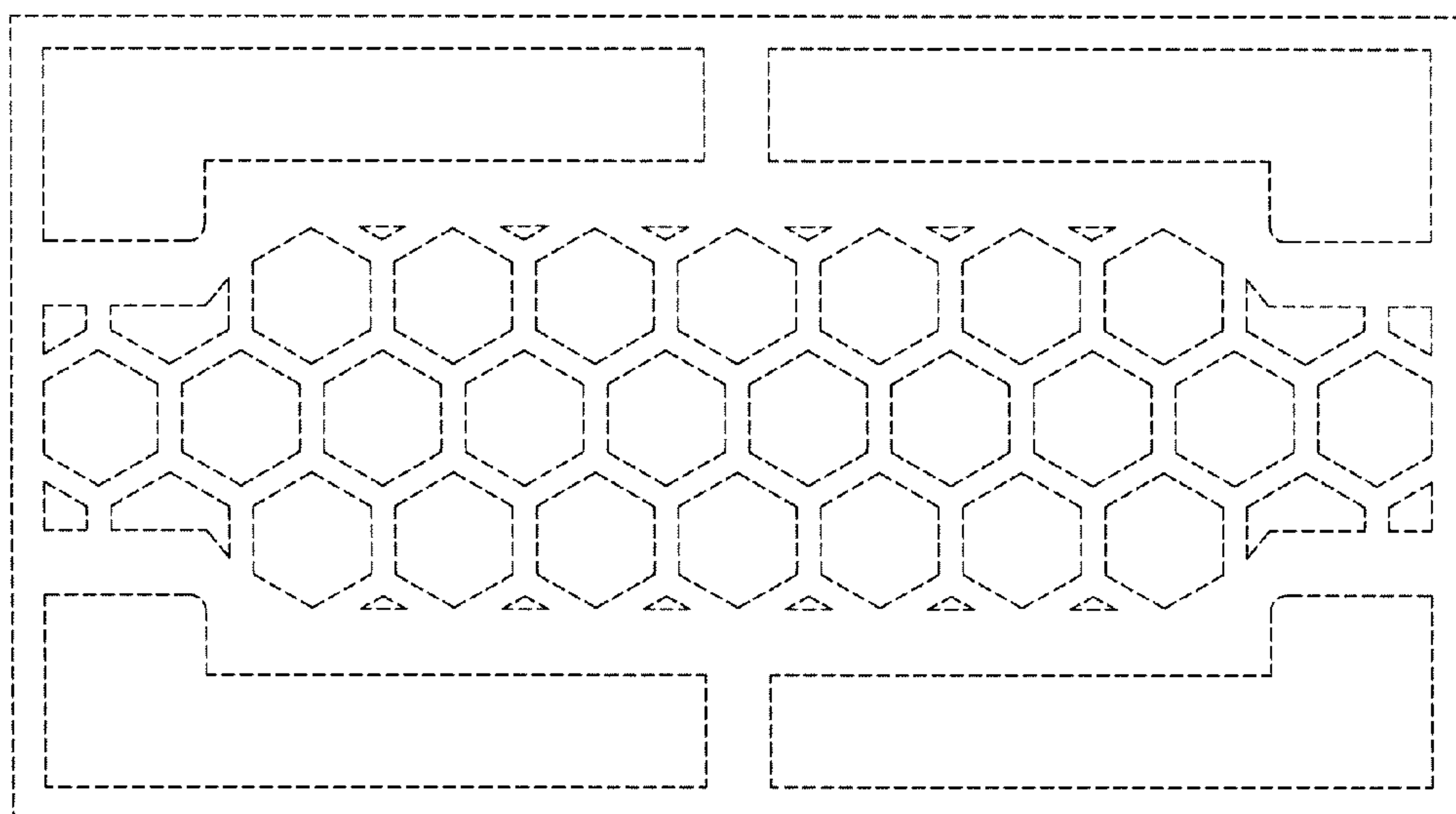


FIG. 7